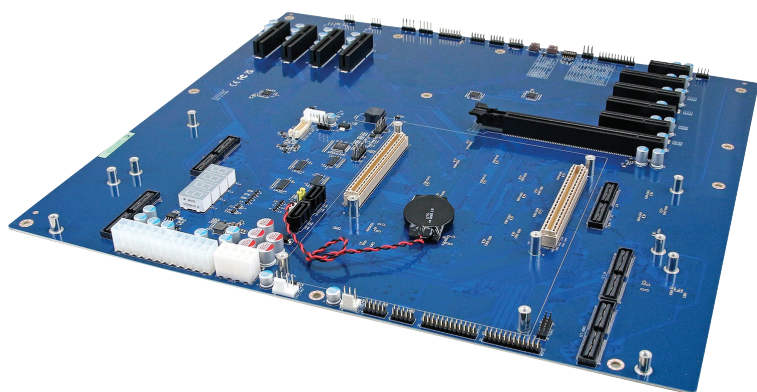


EEV-HC10

EATX Form Factor Carrier Board for COM-HPC Module



Features

- EATX form factor (12" x 13", 305 x 330mm)
- PICMG® COM-HPC® Revision 1.2, COM-HPC client pin-out, size A (95x120mm), B (120x120mm), and C (160x120mm) compatible
- Unmanaged COM-HPC Carrier (C.U.)
- 1 x PCIe x16 Gen5, 8 x PCIe x4, 1 x PCIe x1 for BMC
- Flexible external I/O interfaces via IET modules - more DP/HDMI, USB, USB Type C, LAN ports
- 12-bit GPIO
- 2 x Serial Port/UART

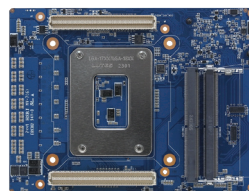
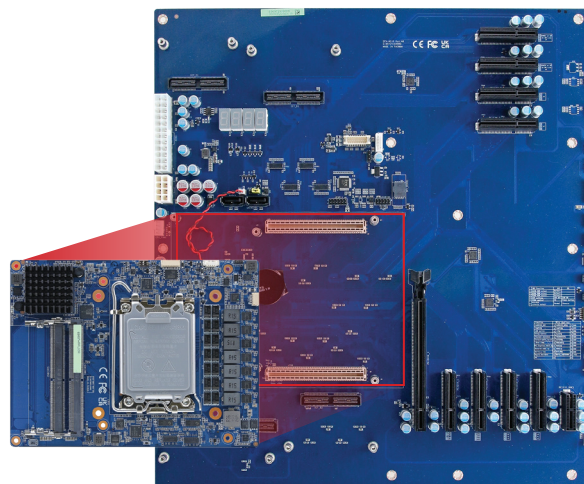
SPECIFICATIONS

I/O

Expansion	1 x PCIe x16 Gen5 socket 8 x PCIe x4 sockets 1 x PCIe x1 socket for BMC
USB	4 x USB3.2 Gen2x2 (Type C) by 2 x IET module 4 x USB2.0 by pin header
SATA	2 x SATAIII
Video	Via IET Modules: 3 x DDI configurable to DP2.1 or HDMI 2.1b by 2 x IET modules 1 x eDP
Audio	Line-out, Mic-in
LAN	Via IET Modules: 2 x 10 or 25 Gigabit Ethernet connector by 1 x IET module 2 x 2.5 Gigabit Ethernet connector by 2 x IET modules
COM Port/UART	2 x Serial Port
DIO	1 x 12-bit GPIO

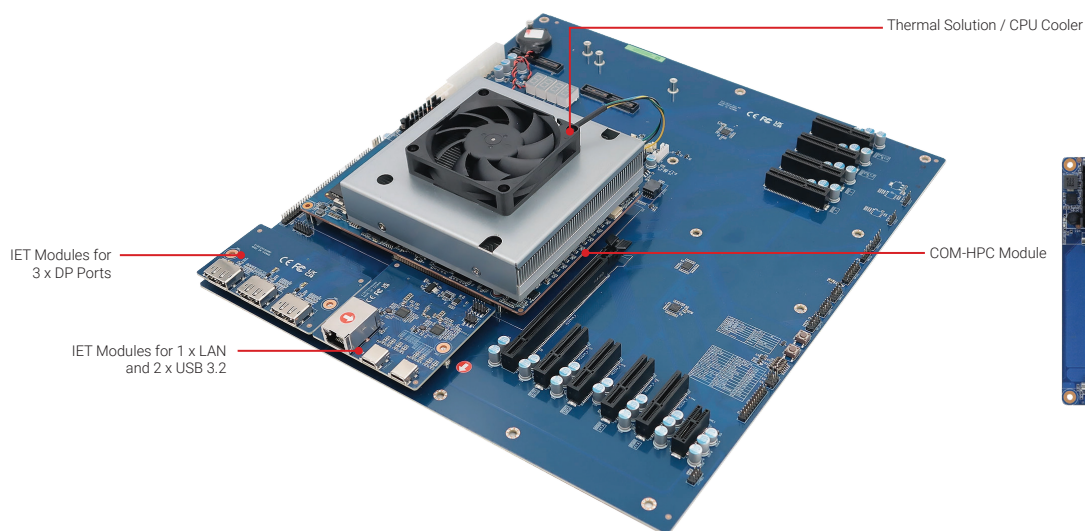
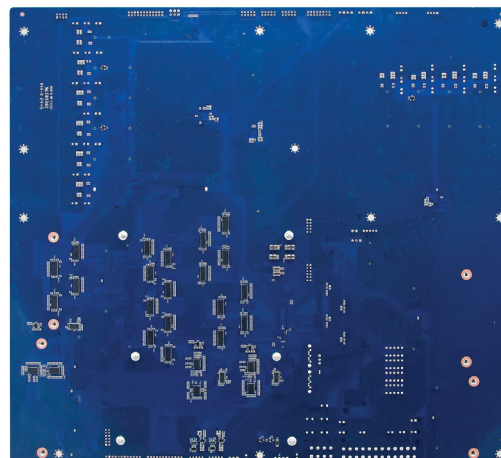
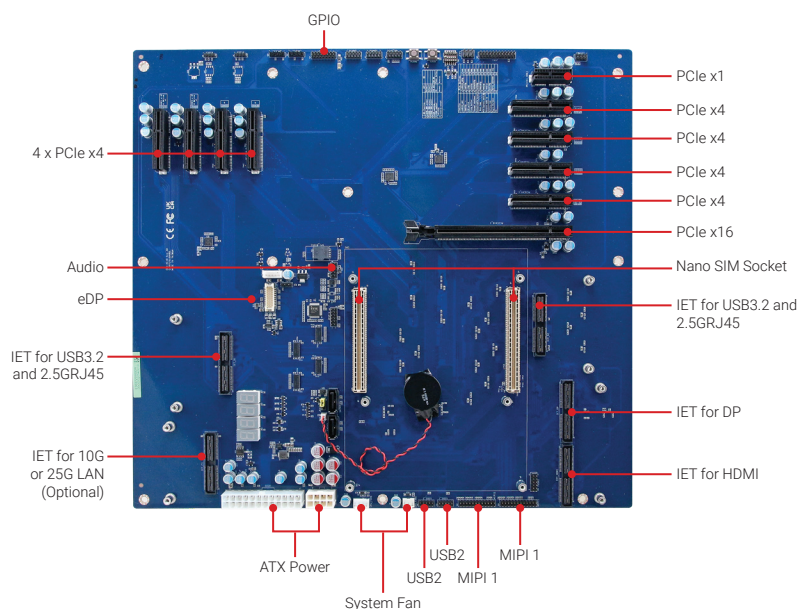
Mechanical, Power, and Environment

Operating Temperature	0°C ~ 60°C (32°F ~ 140°F) with 0.5m/s air flow
Storage Temperature	-20°C ~ 75°C (-4°F ~ 167°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
CE, FCC, RoHS Compliant	CE, FCC, RoHS Compliant
Form Factor	Extended ATX (EATX)
Dimensions	12" x 13" (305 x 330mm)



Compatible with ESM-HRPL
COM-HPC Module

SPECIFICATIONS / ADDITIONAL PRODUCT PHOTOS



Overhead view: ESM-HRPL COM-HPC module with a CPU cooler, mounted on the EEV-HC10 carrier board in the EATX form factor.



ORDERING INFORMATION

Model Name	Description
EEV-HC10-A1R	EATX Carrier Board for COM-HPC Module

PACKING LIST

✓ 1 x EEV-HC10 Board



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